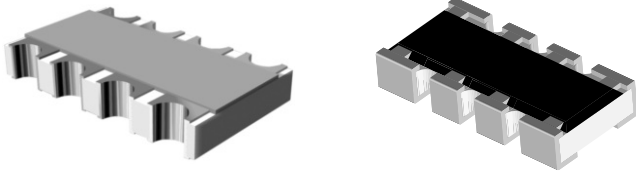


Professional Thin Film Chip Resistor Array



ACAC 0612 (concave terminations) and ACAS 0612 (convex terminations) thin chip resistor arrays combine the proven reliability of professional thin film chip resistor products with the advantages of chip resistor arrays. A small package enables the design of high density circuits in combination with reduction of assembly costs. Four equal resistor values or two pairs are available.

FEATURES

- Advanced thin film technology
- Two pairs or four equal resistor values
- TCR down to ± 25 ppm/K
- Tolerance down to ± 0.5 %
- Pure Sn termination on Ni barrier layer
- RoHS compliant component, compatible with lead (Pb)-free and lead containing soldering processes



APPLICATIONS

- Voltage divider
- Feedback circuits
- Signal conditioning
- Bus terminations

TECHNICAL SPECIFICATIONS	
DESCRIPTION	ACAC 0612, ACAS 0612
EIA size	0612
Metric size	RR1632M
Configuration, isolated	4 x 0603
Design:	
All Equal	AE
Two Pairs	TP
Resistance values	47 Ω to 221 k Ω ⁽¹⁾
Absolute tolerance ⁽²⁾	± 1 %; ± 0.5 %
Absolute temperature coefficient ⁽²⁾	± 50 ppm/K; ± 25 ppm/K
Max. resistance ratio R_{min}/R_{max} .	1:10 ⁽³⁾
Rated dissipation: P_{70} ⁽⁴⁾	
Element	0.1 W
Package, 4 x 0603	0.3 W
Operating voltage	75 V
Film temperature	125 °C
Insulation voltage (U_{ins}) against ambient and between isolated resistors, continuous	75 V

Notes

- ⁽¹⁾ Resistance values to be selected from E24, E48 and E96
 - ⁽²⁾ For TCR tracking, tolerance matching and tighter absolute tolerance please refer to data sheet "Precision Thin Film Chip Resistor Array" available on our web site at www.vishay.com
 - ⁽³⁾ Higher resistance ratio is available on request
 - ⁽⁴⁾ The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat-flow support of the printed circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature is not exceeded. Furthermore, a high level of ambient temperature or of power dissipation may raise the temperature of the solder joint, hence special solder alloys or board materials may be required to maintain the reliability of the assembly.
- These resistors do not feature a limited lifetime when operated within the permissible limits. However, resistance value drift increasing over operating time may result in exceeding a limit acceptable to the specific application, thereby establishing a functional lifetime.

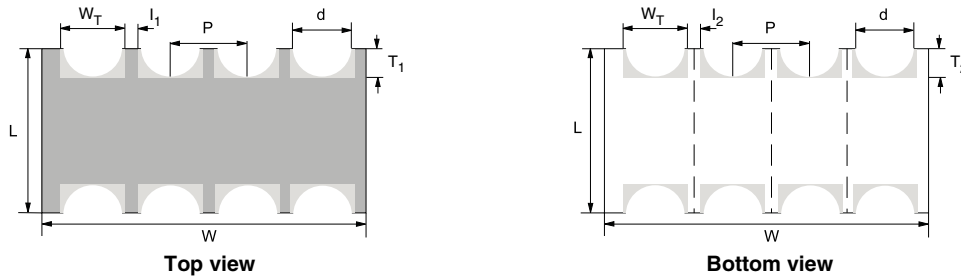
PART NUMBER AND PRODUCT DESCRIPTION (1)																	
PART NUMBER: ACASA110012200P500																	
A	C	A	S	A	1	1	0	0	1	2	2	0	0	P	5	0	0
MODEL	TERMINAL	SIZE	RESISTANCE VALUE (2) (3)		ACCURACY GRADE (4)	RESISTANCE VALUE (2) (3)		PACKAGING (5)		SPECIAL							
ACA	C = Concave S = Convex	A = 0612	3 digit resistance value R1, R4 1 digit multiplier MULTIPLIER 9 = *10 ⁻¹ 0 = *10 ⁰ 1 = *10 ¹ 2 = *10 ² 3 = *10 ³		TCR and Tolerance 1 2 3	3 digit resistance value R2, R3 1 digit multiplier MULTIPLIER 9 = *10 ⁻¹ 0 = *10 ⁰ 1 = *10 ¹ 2 = *10 ² 3 = *10 ³		P1 P5 PW		00 = Standard							
PRODUCT DESCRIPTION: ACAS 0612 110R 1 220R P5																	
ACA	S	0612	110R		1	220R		P5									
MODEL	TERMINATION	SIZE	RESISTANCE VALUE R1, R4 (2) (3)		ACCURACY GRADE (4)	RESISTANCE VALUE R2, R3 (2) (3)		PACKAGING (5)									
ACA = Chip Array	C = Concave S = Convex	0612	110R = 110 Ω 1K1 = 1.1 kΩ 22K1 = 22.1 kΩ		TCR and Tolerance 1 2 3	220R = 220 Ω 1K1 = 1.1 kΩ 22K1 = 22.1 kΩ		P1 P5 PW									

Notes

- (1) Products can be ordered using either the PART NUMBER or the PRODUCT DESCRIPTION
- (2) Please refer to APPLICATION INFORMATION, see below
- (3) Different resistance values are available on request
- (4) Please refer to table TEMPERATURE COEFFICIENT AND RESISTANCE RANGE, see below
- (5) Please refer to table PACKAGING, see below

PACKAGING					
MODEL	TAPE WIDTH	DIAMETER	PIECES	PITCH	PACKAGING CODE
					PAPER TAPE
ACAC 0612	8 mm	180 mm/7"	1000	4 mm	P1
	8 mm	180 mm/7"	5000	4 mm	P5
ACAS 0612	8 mm	330 mm/13"	10 000	4 mm	PW

DIMENSIONS ACAC 0612 in millimeters



DIMENSIONS - chip resistor array, mass and relevant physical dimensions											
TYPE	L (mm)	W (mm)	H (mm)	P (mm)	WT (mm)	T1 (mm)	T2 (mm)	d (mm)	l1 (mm)	l2 (mm)	MASS (mg)
ACAC 0612	1.6 ± 0.15	3.2 ± 0.15	0.55 ± 0.1	0.8 ± 0.1	0.5 ± 0.15	0.3 ± 0.15	0.4 ± 0.15	0.3 ± 0.1	min. 0.15	min. 0.25	9.41

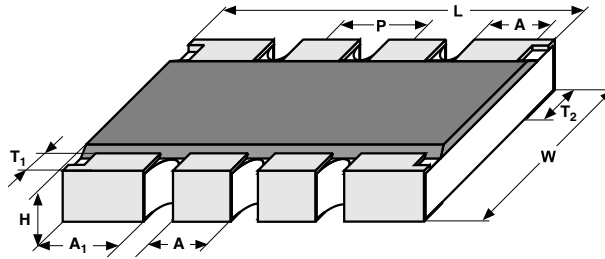
ACAC 0612, ACAS 0612 - Professional

Vishay Beyschlag

Professional Thin Film Chip Resistor Array

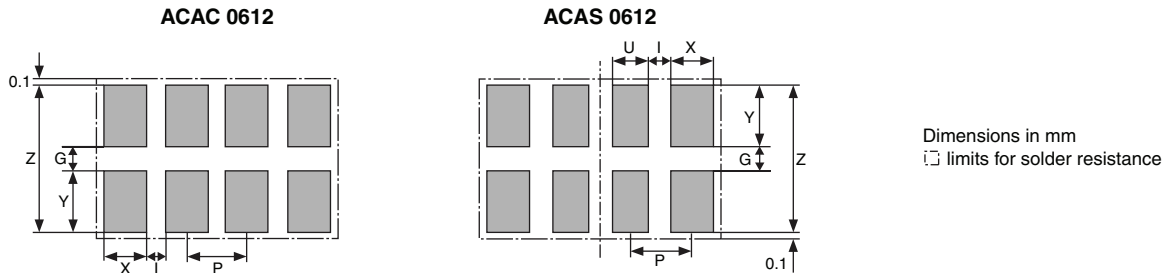


DIMENSIONS ACAS 0612 in millimeters



DIMENSIONS - chip resistor array, mass and relevant physical dimensions									
TYPE	W (mm)	L (mm)	H (mm)	P (mm)	A ₁ (mm)	A (mm)	T ₁ (mm)	T ₂ (mm)	MASS (mg)
ACAS 0612	1.5 ± 0.15	3.2 ± 0.15	0.45 ± 0.1	0.8 ± 0.1	0.6 ± 0.15	0.4 ± 0.15	0.3 ± 0.15	0.4 ± 0.15	9.41

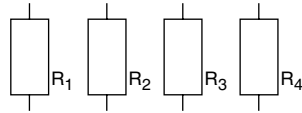
PATTERN STYLES FOR CHIP RESISTOR ARRAYS



RECOMMENDED SOLDER PAD DIMENSIONS FOR CHIP RESISTOR ARRAYS							
TYPE	G (mm)	Y (mm)	X (mm)	U (mm)	Z (mm)	I (mm)	P (mm)
ACAC 0612	0.7	0.7	0.5	-	2.1	0.3	0.8
ACAS 0612	0.8	1.15	0.63	0.44	3.1	0.36	0.8

TEMPERATURE COEFFICIENT AND RESISTANCE RANGE			
DESCRIPTION			RESISTANCE VALUE
ACCURACY GRADE	ABSOLUTE TCR	ABSOLUTE TOLERANCE	ACAC 0612, ACAS 0612
1	± 25 ppm/K	± 0.5 %	47 Ω to 221 kΩ
2	± 50 ppm/K	± 0.5 %	47 Ω to 221 kΩ
3	± 50 ppm/K	± 1 %	47 Ω to 221 kΩ

APPLICATION INFORMATION



Circuit Type 03

DESCRIPTION

The production of the components is strictly controlled and follows an extensive set of instructions established for reproducibility. A homogeneous film of metal alloy is deposited on a high grade (96 % Al_2O_3) ceramic substrate and conditioned to achieve the desired temperature coefficient. Specially designed inner contacts are realised on both sides. A special laser is used to achieve the target value by smoothly cutting a meander groove in the resistive layer without damaging the ceramics.

The resistor elements are covered by a protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure tin on nickel plating.

The result of the determined production is verified by an extensive testing procedure and optical inspection performed on 100 % of the individual chip resistors. Only accepted products are laid directly into the paper tape in accordance with **IEC 60286-3***.

ASSEMBLY

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using reflow or vapour phase as shown in **IEC 61760-1***. For ACAC resistor arrays automatic soldering using can also be used. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions.

The suitability of conformal coatings, if applied, shall be qualified by appropriate means to ensure the long-term stability of the whole system. The resistors are RoHS compliant; the pure tin plating provides compatibility with lead (Pb)-free and lead-containing soldering processes. The permitted storage time is 20 years, whereas the solderability is specified for 2 years after production or requalification. The immunity of the plating against tin whisker growth has been proven under extensive testing.

All products comply with the **GADSL**⁽¹⁾ and the **CEFIC-EECA-EICTA**⁽²⁾ list of legal restrictions on hazardous substances. This includes full compliance with the following directives:

- 2000/53/EC End of Vehicle life Directive (ELV) an Annex II (ELV II)
- 2002/95/EC Restriction of the use of Hazardous Substances directive (RoHS)
- 2002/96/EC Waste Electrical and Electronic Equipment Directive (WEEE)

APPROVALS

Where applicable, the resistors are tested in accordance with **EN 140401-801** which refers to **EN 60115-1** and **EN 140400**.

Notes

⁽¹⁾ Global Automotive Declarable Substance List, see www.gadsl.org

⁽²⁾ CEFIC (European Chemical Industry Council), EECA (European Electronic Component Manufacturers Association), EICTA (European trade organisation representing the information and communications technology and consumer electronics), see www.eicta.org → issues → environment policy → chemicals → chemicals for electronics

- The quoted IEC standards marked with an asterisk (*) are also released as EN standards with the same number and identical contents

TESTS AND REQUIREMENTS

Essentially all tests are carried out in accordance with the following specifications:

EN 60115-1, Generic specification (includes tests)

EN 140400, Sectional specification (includes schedule for qualification approval)

The testing also covers most of the requirements specified by EIA/IS-703 and JIS-C-5202.

The tests are carried out in accordance with **IEC 60068*** and under standard atmospheric conditions according to **IEC 60068-1***, 5.3. Climatic category LCT/UCT/56 (rated temperature range: Lower Category Temperature, Upper

Category Temperature; damp heat, long term, 56 days) is valid.

Unless otherwise specified the following values apply:

Temperature: 15 °C to 35 °C

Relative humidity: 45 % to 75 %

Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar)

In the following table only the tests and requirements are listed with reference to the relevant clauses of **EN 60115-1** and **IEC 60068-2***; a short description of the test procedure is also given.

TEST PROCEDURES AND REQUIREMENTS				
EN 60115-1 CLAUSE	IEC 60068-2* TEST METHOD	TEST	PROCEDURE	REQUIREMENTS ⁽¹⁾ PERMISSIBLE CHANGE (ΔR)
			Stability for product types: ACAC 0612, ACAS 0612	47 Ω to 221 k Ω
			Climatic category (LCT/UCT/duration)	- 55 °C/+ 125 °C/56 days
4.5	-	Resistance	-	$\pm 1 \%$; $\pm 0.5 \%$; $\pm 0.25 \%$
4.8.4.2	-	Temperature coefficient	At 20/LCT/ 20 °C and 20/UCT/20 °C	± 50 ppm/K; ± 25 ppm/K
4.25.1	-	Endurance	$U = \sqrt{P_{70}} \times R$ or $U = U_{max.}$; 1.5 h on; 0.5 h off; 70 °C; 1000 h	$\pm (0.25 \% R + 0.05 \Omega)$
4.25.3	-	Endurance at upper category temperature	125 °C; 1000 h	$\pm (0.25 \% R + 0.05 \Omega)$
4.24	78 (Cab)	Damp heat, steady state	(40 ± 2) °C; 56 days; (93 ± 3) % RH	$\pm (0.5 \% R + 0.05 \Omega)$
4.13	-	Short time overload ⁽²⁾	$U = 2.5 \times \sqrt{P_{70}} \times R$ or $U = 2 \times U_{max.}$; 5 s	$\pm (0.1 \% R + 0.01 \Omega)$ no visible damage
4.19	14 (Na)	Rapid change of temperature	30 min at LCT and 30 min at UCT; 5 cycles	$\pm (0.1 \% R + 0.01 \Omega)$ no visible damage
4.18.2	58 (Td)	Resistance to soldering heat	Reflow method 2 (IR/forced gas convection); (260 ± 5) °C; (10 ± 1) s	$\pm (0.25 \% R + 0.01 \Omega)$ no visible damage
4.17.2	58 (Td)	Solderability	Solder bath method; SnPb; non-activated flux accelerated ageing 4 h/155 °C (215 ± 3) °C; (3 ± 0.3) s Solder bath method; SnAgCu; non-activated flux accelerated ageing 4 h/155 °C (245 ± 3) °C; (3 ± 0.3) s	Good tinning ($\geq 95 \%$ covered); no visible damage
4.32	21 (Ue ₃)	Shear (adhesion)	45 N	No visible damage
4.33	21 (Ue ₁)	Substrate bending	Depth 2 mm, 3 times	$\pm (0.1 \% R + 0.01 \Omega)$ no visible damage; no open circuit in bent position
4.7	-	Voltage proof	$U_{rms} = U_{ins}$ 60 ± 5 s; against ambient, between adjacent resistors	No flashover or breakdown

Notes

⁽¹⁾ Figures are given for equal values

⁽²⁾ For a single element

- The quoted IEC standards marked with an asterisk (*) are also released as EN standards with the same number and identical contents